

Product Change Notification / LIAL-23USLU235

Date:

13-Feb-2021

Product Category:

8-bit Microcontrollers, Interface- Controller Area Network (CAN), Interface- Serial Peripherals

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3979 and 3979.001 Final Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site.

Affected CPNs:

LIAL-23USLU235_Affected_CPN_02132021.pdf LIAL-23USLU235_Affected_CPN_02132021.csv

Notification Text:

PCN Status: Final notification.

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the attachments found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .csv).

Description of Change:Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site.

Pre Change: Using 3280 die attach material

Post Change:

Using QMI-519 die attach material

Pre and Post Change Summary:

	Pre Change	Post Change				
	Microchip Technology	Microchip Technology				
Assembly Site	Thailand	Thailand				
	(MTAI)	(MTAI)				
Wire material	CuPdAu	CuPdAu				
Die attach material	3280	QMI-519				
Molding compound material	G600	G600				
Lead frame material	C194	C194				

Impacts to Data Sheet: None

Change Impact:None

Reason for Change:To improve productivity by qualifyingQMI-519 die attach material

Change Implementation Status: In Progress

Estimated First Ship Date: February 28, 2021 (date code: 2110)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

	October 2020					February 2021					
Workweek	40	41	42	43	44	->	06	07	08	09	10
Initial PCN Issue Date		Х									
Qual Report Availability								Х			
Final PCN Issue Date								Х			
Estimated Implementation Date											Х

Method to Identify Change: Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:October 12, 2020: Issued initial notification.

February 13, 2021: Issued final notification. Attached the qualification report. Provided estimated first ship date to be on February 28, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

PCN_LIAL-23USLU235_Qual_Report.pdf

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to <u>receive Microchip PCNs via email</u> please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to <u>change your PCN profile</u>, <u>including opt out</u>, please go to the <u>PCN home page</u> select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections. LIAL-23USLU235 - CCB 3979 and 3979.001 Final Notice: Qualification of QMI-519 die attach material for selected products available in 28L SOIC (.300in) and 18L SOIC (.300in) packages at MTAI assembly site.

Affected Catalog Part Numbers (CPN)

MCP23017-E/SO MCP23017T-E/SO MCP23S17-E/SO MCP23S17T-E/SO PIC16F57-E/SO PIC16F57-I/SO MCV28A-I/SO PIC16F57T-I/SO028 PIC16F57T-I/SO PIC16F57T-E/SO PIC16F570-I/SO MCP23018-E/SO MCP23018T-E/SO MCP23S18-E/SO MCP23S18T-E/SO PIC16LF1902-I/SO PIC16LF1903-I/SO PIC16F723A-E/SO PIC16F723A-I/SO PIC16F723AT-I/SO PIC16F722A-E/SO PIC16F722A-I/SO PIC16F722AT-I/SO PIC16LF723A-E/SO PIC16LF723A-I/SO PIC16LF722A-E/SO PIC16LF722A-I/SO PIC16CR54CT-20/SO012 CF745-04/SO PIC16LC54C-04/SO PIC16C54C-04/SO PIC16C54C-20/SO PIC16C54C-04/SOC04 PIC16C54C-20E/SO PIC16LC54C-04I/SO PIC16C54C-04I/SO PIC16C54C-20I/SO PIC16C54CT-20/SO068 PIC16LC54CT-04/SO150 PIC16C54CT-04/SO PIC16C54CT-04I/SO104 PIC16C54CT-04I/SO MCP23008-E/SO MCP23008T-E/SO MCP23S08-E/SO MCP23S08T-E/SO

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MCP2515-E/SO MCP2515-E/SORB2 MCP2515-E/SORB4 MCP2515-I/SO MCP2515-I/SORB2 MCP2515-I/SORB4 MCP2515T-I/SO MCP2515T-I/SORB2 MCP2515T-I/SORB4 MCP2515T-E/SO MCP2515T-E/SORB2 MCP2515T-E/SORB4 PIC16F54-E/SO PIC16F54-I/SO023 PIC16F54-I/SO043 PIC16F54-I/SO PIC16F54T-I/SO036 PIC16F54T-I/SO042 PIC16F54T-I/SO PIC16F54T-E/SO040 PIC16F716-E/SO PIC16F716-I/SO PIC16F716T-I/SO048 PIC16F716T-I/SO061 PIC16F716T-I/SO PIC16F716T-E/SO